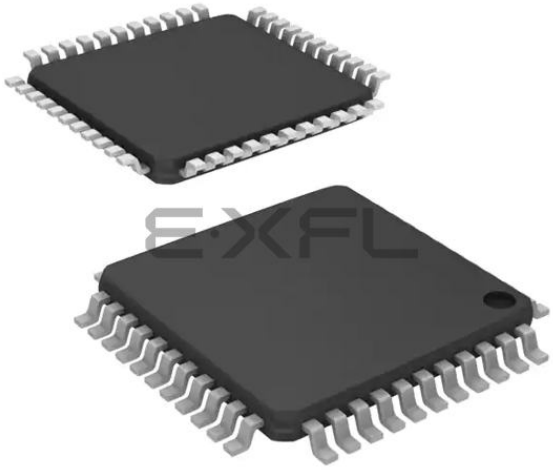

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	16MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	33
Program Memory Size	8KB (4K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	454 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c43t-16e-pt

FIGURE 3-1: PIC17C42 BLOCK DIAGRAM

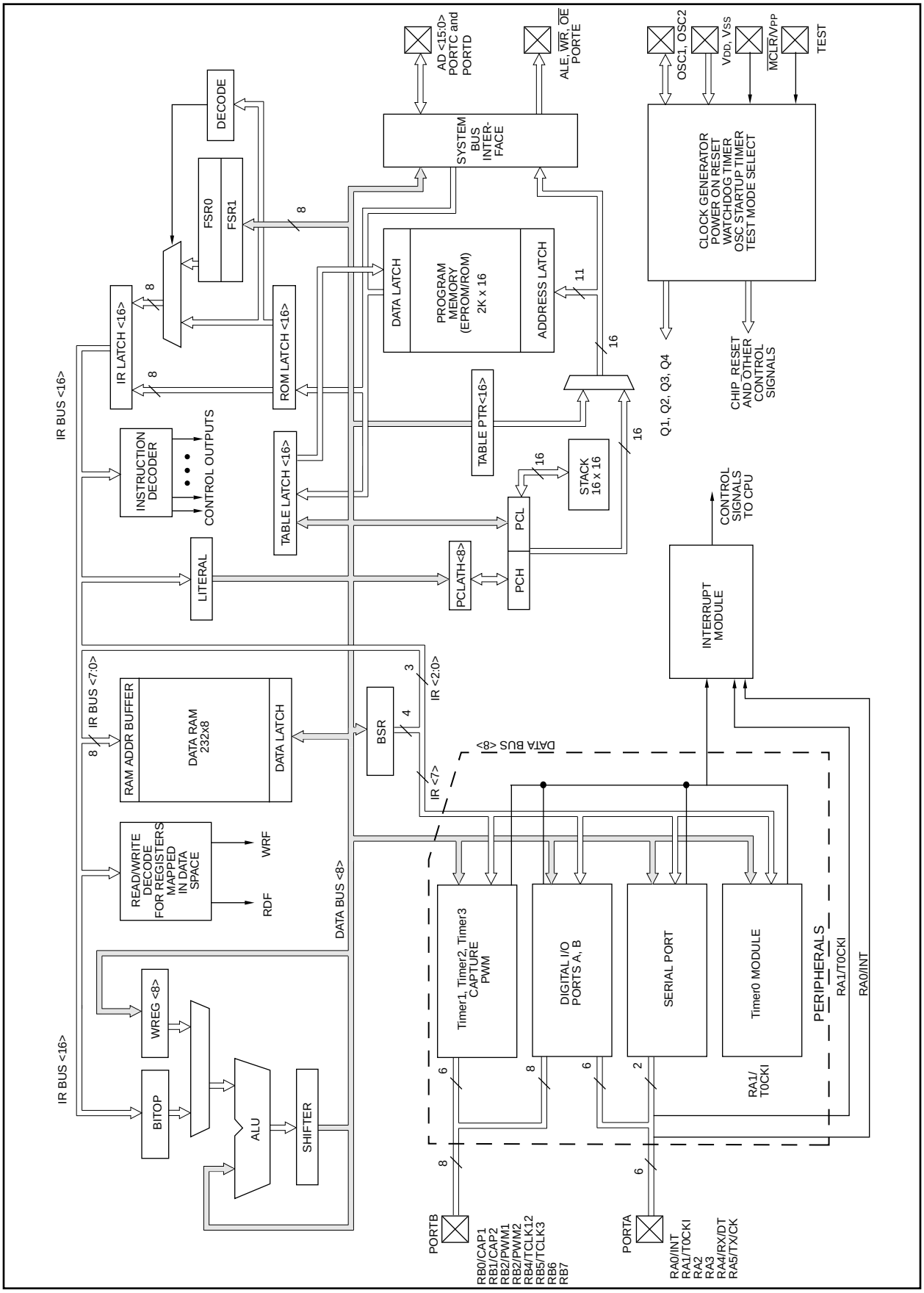
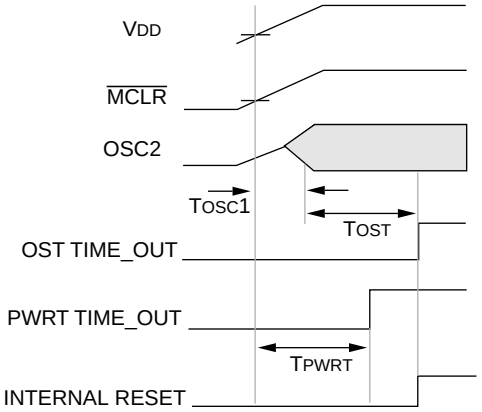


FIGURE 4-5: OSCILLATOR START-UPTIME



This figure shows in greater detail the timings involved with the oscillator start-up timer. In this example the low frequency crystal start-up time is larger than power-up time (TPWRT).
Tosc1 = time for the crystal oscillator to react to an oscillation level detectable by the Oscillator Start-up Timer (ost).
TOST = 1024TOSC.

FIGURE 4-6: USING ON-CHIP POR

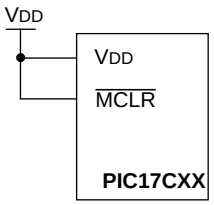
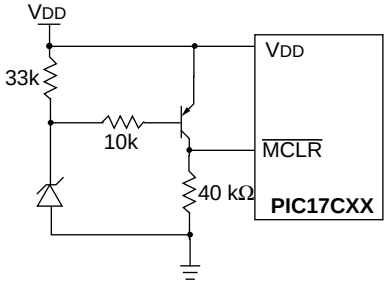
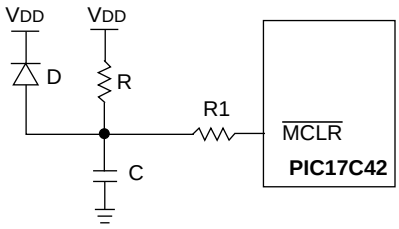


FIGURE 4-7: BROWN-OUT PROTECTION CIRCUIT 1



This circuit will activate reset when VDD goes below (Vz + 0.7V) where Vz = Zener voltage.

FIGURE 4-8: PIC17C42 EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)

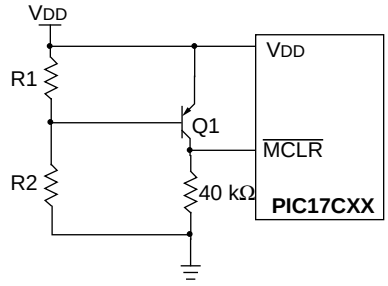


Note 1: An external Power-on Reset circuit is required only if VDD power-up time is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to ensure that the voltage drop across R does not exceed 0.2V (max. leakage current spec. on the MCLR/VPP pin is 5 μA). A larger voltage drop will degrade VIH level on the MCLR/VPP pin.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into MCLR from external capacitor C in the event of MCLR/VPP pin breakdown due to Electrostatic Discharge (ESD) or (Electrical Overstress) EOS.

FIGURE 4-9: BROWN-OUT PROTECTION CIRCUIT 2



This brown-out circuit is less expensive, albeit less accurate. Transistor Q1 turns off when VDD is below a certain level such that:

$$V_{DD} \bullet \frac{R1}{R1 + R2} = 0.7V$$

5.2 Peripheral Interrupt Enable Register (PIE)

This register contains the individual flag bits for the Peripheral interrupts.

FIGURE 5-3: PIE REGISTER (ADDRESS: 17h, BANK 1)

R/W - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0
RBIE	TMR3IE	TMR2IE	TMR1IE	CA2IE	CA1IE	TXIE	RCIE
bit7							bit0

R = Readable bit
W = Writable bit
-n = Value at POR reset

bit 7: **RBIE**: PORTB Interrupt on Change Enable bit
1 = Enable PORTB interrupt on change
0 = Disable PORTB interrupt on change

bit 6: **TMR3IE**: Timer3 Interrupt Enable bit
1 = Enable Timer3 interrupt
0 = Disable Timer3 interrupt

bit 5: **TMR2IE**: Timer2 Interrupt Enable bit
1 = Enable Timer2 interrupt
0 = Disable Timer2 interrupt

bit 4: **TMR1IE**: Timer1 Interrupt Enable bit
1 = Enable Timer1 interrupt
0 = Disable Timer1 interrupt

bit 3: **CA2IE**: Capture2 Interrupt Enable bit
1 = Enable Capture interrupt on RB1/CAP2 pin
0 = Disable Capture interrupt on RB1/CAP2 pin

bit 2: **CA1IE**: Capture1 Interrupt Enable bit
1 = Enable Capture interrupt on RB2/CAP1 pin
0 = Disable Capture interrupt on RB2/CAP1 pin

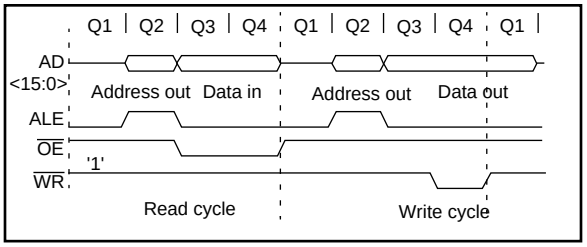
bit 1: **TXIE**: USART Transmit Interrupt Enable bit
1 = Enable Transmit buffer empty interrupt
0 = Disable Transmit buffer empty interrupt

bit 0: **RCIE**: USART Receive Interrupt Enable bit
1 = Enable Receive buffer full interrupt
0 = Disable Receive buffer full interrupt

6.1.2 EXTERNAL MEMORY INTERFACE

When either microprocessor or extended microcontroller mode is selected, PORTC, PORTD and PORTE are configured as the system bus. PORTC and PORTD are the multiplexed address/data bus and PORTE is for the control signals. External components are needed to demultiplex the address and data. This can be done as shown in Figure 6-4. The waveforms of address and data are shown in Figure 6-3. For complete timings, please refer to the electrical specification section.

FIGURE 6-3: EXTERNAL PROGRAM MEMORY ACCESS WAVEFORMS



The system bus requires that there is no bus conflict (minimal leakage), so the output value (address) will be capacitively held at the desired value.

As the speed of the processor increases, external EPROM memory with faster access time must be used. Table 6-2 lists external memory speed requirements for a given PIC17C4X device frequency.

In extended microcontroller mode, when the device is executing out of internal memory, the control signals will continue to be active. That is, they indicate the action that is occurring in the internal memory. The external memory access is ignored.

This following selection is for use with Microchip EPROMs. For interfacing to other manufacturers memory, please refer to the electrical specifications of the desired PIC17C4X device, as well as the desired memory device to ensure compatibility.

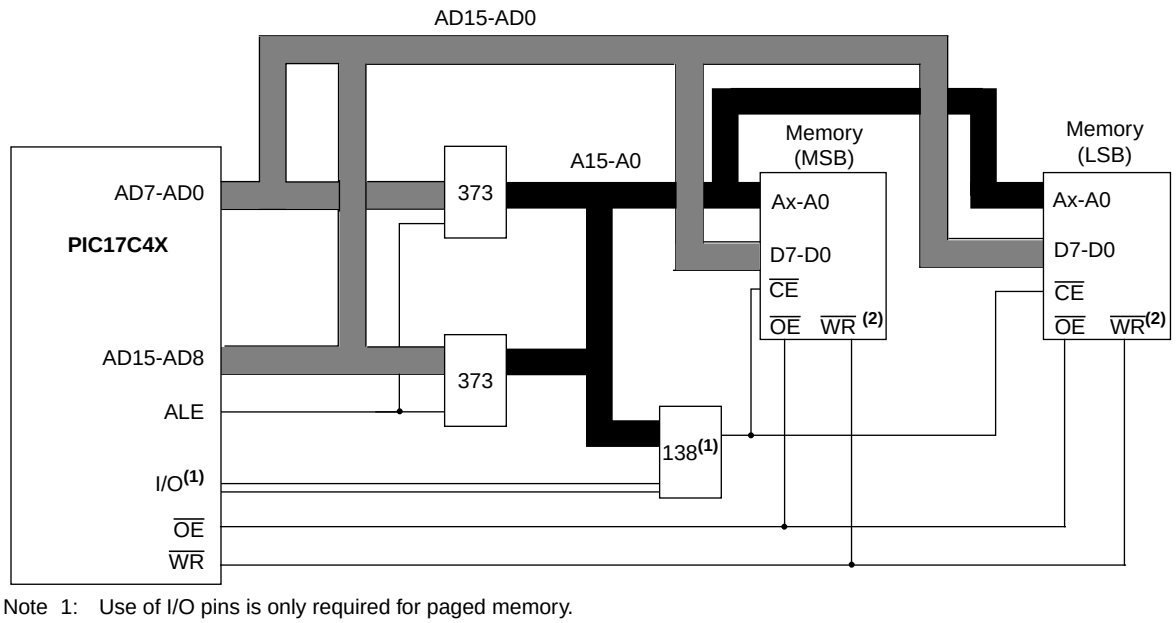
TABLE 6-2: EPROM MEMORY ACCESS TIME ORDERING SUFFIX

PIC17C4X Oscillator Frequency	Instruction Cycle Time (TCY)	EPROM Suffix	
		PIC17C42	PIC17C43 PIC17C44
8 MHz	500 ns	-25	-25
16 MHz	250 ns	-12	-15
20 MHz	200 ns	-90	-10
25 MHz	160 ns	N.A.	-70
33 MHz	121 ns	N.A.	(1)

Note 1: The access times for this requires the use of fast SRAMS.

Note: The external memory interface is not supported for the LC devices.

FIGURE 6-4: TYPICAL EXTERNAL PROGRAM MEMORY CONNECTION DIAGRAM



Note 1: Use of I/O pins is only required for paged memory.
2: This signal is unused for ROM and EPROM devices.

6.2 Data Memory Organization

Data memory is partitioned into two areas. The first is the General Purpose Registers (GPR) area, while the second is the Special Function Registers (SFR) area. The SFRs control the operation of the device.

Portions of data memory are banked, this is for both areas. The GPR area is banked to allow greater than 232 bytes of general purpose RAM. SFRs are for the registers that control the peripheral functions. Banking requires the use of control bits for bank selection. These control bits are located in the Bank Select Register (BSR). If an access is made to a location outside this banked region, the BSR bits are ignored. Figure 6-5 shows the data memory map organization for the PIC17C42 and Figure 6-6 for all of the other PIC17C4X devices.

Instructions MOVPF and MOVFP provide the means to move values from the peripheral area (“P”) to any location in the register file (“F”), and vice-versa. The definition of the “P” range is from 0h to 1Fh, while the “F” range is 0h to FFh. The “P” range has six more locations than peripheral registers (eight locations for the PIC17C42 device) which can be used as General Purpose Registers. This can be useful in some applications where variables need to be copied to other locations in the general purpose RAM (such as saving status information during an interrupt).

The entire data memory can be accessed either directly or indirectly through file select registers FSR0 and FSR1 (Section 6.4). Indirect addressing uses the appropriate control bits of the BSR for accesses into the banked areas of data memory. The BSR is explained in greater detail in Section 6.8.

6.2.1 GENERAL PURPOSE REGISTER (GPR)

All devices have some amount of GPR area. The GPRs are 8-bits wide. When the GPR area is greater than 232, it must be banked to allow access to the additional memory space.

Only the PIC17C43 and PIC17C44 devices have banked memory in the GPR area. To facilitate switching between these banks, the MOVLR bank instruction has been added to the instruction set. GPRs are not initialized by a Power-on Reset and are unchanged on all other resets.

6.2.2 SPECIAL FUNCTION REGISTERS (SFR)

The SFRs are used by the CPU and peripheral functions to control the operation of the device (Figure 6-5 and Figure 6-6). These registers are static RAM.

The SFRs can be classified into two sets, those associated with the “core” function and those related to the peripheral functions. Those registers related to the “core” are described here, while those related to a peripheral feature are described in the section for each peripheral feature.

The peripheral registers are in the banked portion of memory, while the core registers are in the unbanked region. To facilitate switching between the peripheral banks, the MOVLB bank instruction has been provided.

6.3 Stack Operation

The PIC17C4X devices have a 16 x 16-bit wide hardware stack (Figure 6-1). The stack is not part of either the program or data memory space, and the stack pointer is neither readable nor writable. The PC is "PUSHed" onto the stack when a CALL instruction is executed or an interrupt is acknowledged. The stack is "POPed" in the event of a RETURN, RETLW, or a RETFIE instruction execution. PCLATH is not affected by a "PUSH" or a "POP" operation.

The stack operates as a circular buffer, with the stack pointer initialized to '0' after all resets. There is a stack available bit (STKAV) to allow software to ensure that the stack has not overflowed. The STKAV bit is set after a device reset. When the stack pointer equals Fh, STKAV is cleared. When the stack pointer rolls over from Fh to 0h, the STKAV bit will be held clear until a device reset.

Note 1: There is not a status bit for stack underflow. The STKAV bit can be used to detect the underflow which results in the stack pointer being at the top of stack.

Note 2: There are no instruction mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW, and RETFIE instructions, or the vectoring to an interrupt vector.

Note 3: After a reset, if a "POP" operation occurs before a "PUSH" operation, the STKAV bit will be cleared. This will appear as if the stack is full (underflow has occurred). If a "PUSH" operation occurs next (before another "POP"), the STKAV bit will be locked clear. Only a device reset will cause this bit to set.

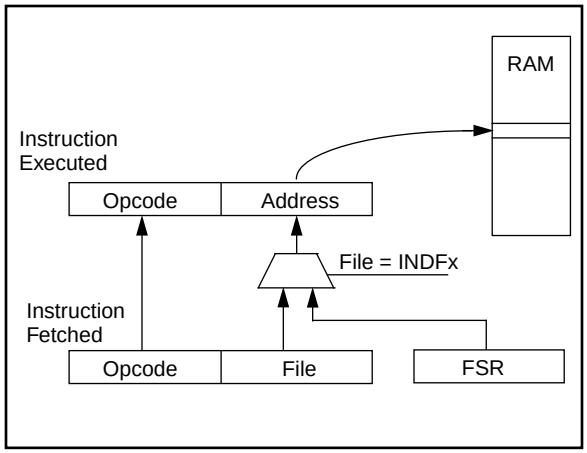
After the device is "PUSHed" sixteen times (without a "POP"), the seventeenth push overwrites the value from the first push. The eighteenth push overwrites the second push (and so on).

6.4 Indirect Addressing

Indirect addressing is a mode of addressing data memory where the data memory address in the instruction is not fixed. That is, the register that is to be read or written can be modified by the program. This can be useful for data tables in the data memory. Figure 6-10 shows the operation of indirect addressing. This shows the moving of the value to the data memory address specified by the value of the FSR register.

Example 6-1 shows the use of indirect addressing to clear RAM in a minimum number of instructions. A similar concept could be used to move a defined number of bytes (block) of data to the USART transmit register (TXREG). The starting address of the block of data to be transmitted could easily be modified by the program.

FIGURE 6-10: INDIRECT ADDRESSING



12.1.2 TIMER1 & TIMER2 IN 16-BIT MODE

To select 16-bit mode, the T16 bit must be set. In this mode TMR1 and TMR2 are concatenated to form a 16-bit timer (TMR2:TMR1). The 16-bit timer increments until it matches the 16-bit period register (PR2:PR1). On the following timer clock, the timer value is reset to 0h, and the TMR1IF bit is set.

When selecting the clock source for the16-bit timer, the TMR1CS bit controls the entire 16-bit timer and TMR2CS is a “don’t care.” When TMR1CS is clear, the timer increments once every instruction cycle (Fosc/4). When TMR1CS is set, the timer increments on every falling edge of the RB4/TCLK12 pin. For the 16-bit timer to increment, both TMR1ON and TMR2ON bits must be set (Table 12-1).

12.1.2.1 EXTERNAL CLOCK INPUT FOR TMR1:TMR2

When TMR1CS is set, the 16-bit TMR2:TMR1 increments on the falling edge of clock input TCLK12. The input on the RB4/TCLK12 pin is sampled and synchronized by the internal phase clocks twice every instruction cycle. This causes a delay from the time a falling edge appears on RB4/TCLK12 to the time TMR2:TMR1 is actually incremented. For the external clock input timing requirements, see the Electrical Specification section.

TABLE 12-1: TURNING ON 16-BIT TIMER

TMR2ON	TMR1ON	Result
1	1	16-bit timer (TMR2:TMR1) ON
0	1	Only TMR1 increments
x	0	16-bit timer OFF

FIGURE 12-4: TMR1 AND TMR2 IN 16-BIT TIMER/COUNTER MODE

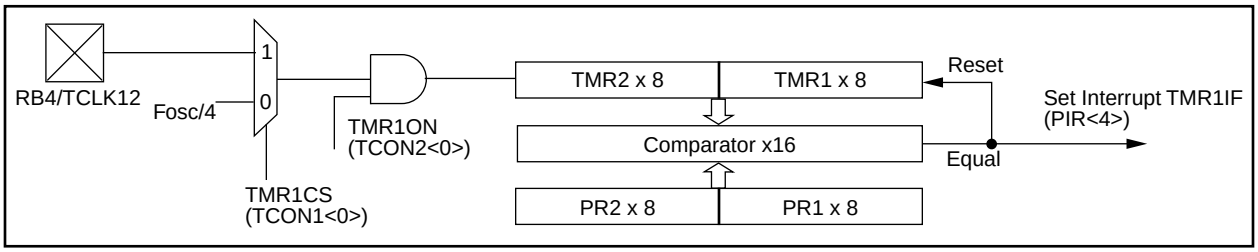


TABLE 12-2: SUMMARY OF TIMER1 AND TIMER2 REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other resets (Note1)
16h, Bank 3	TCON1	CA2ED1	CA2ED0	CA1ED1	CA1ED0	T16	TMR3CS	TMR2CS	TMR1CS	0000 0000	0000 0000
17h, Bank 3	TCON2	CA2OVF	CA1OVF	PWM2ON	PWM1ON	CA1/$\overline{PR3}$	TMR3ON	TMR2ON	TMR1ON	0000 0000	0000 0000
10h, Bank 2	TMR1	Timer1 register								xxxx xxxx	uuuu uuuu
11h, Bank 2	TMR2	Timer2 register								xxxx xxxx	uuuu uuuu
16h, Bank 1	PIR	RBIF	TMR3IF	TMR2IF	TMR1IF	CA2IF	CA1IF	TXIF	RCIF	0000 0010	0000 0010
17h, Bank 1	PIE	RBIE	TMR3IE	TMR2IE	TMR1IE	CA2IE	CA1IE	TXIE	RCIE	0000 0000	0000 0000
07h, Unbanked	INTSTA	PEIF	T0CKIF	T0IF	INTF	PEIE	T0CKIE	T0IE	INTE	0000 0000	0000 0000
06h, Unbanked	CPUSTA	—	—	STKAV	GLINTD	$\overline{TO}$	$\overline{PD}$	—	—	--11 11--	--11 qq--
14h, Bank 2	PR1	Timer1 period register								xxxx xxxx	uuuu uuuu
15h, Bank 2	PR2	Timer2 period register								xxxx xxxx	uuuu uuuu
10h, Bank 3	PW1DCL	DC1	DC0	—	—	—	—	—	—	xx-- ----	uu-- ----
11h, Bank 3	PW2DCL	DC1	DC0	TM2PW2	—	—	—	—	—	xx0- ----	uu0- ----
12h, Bank 3	PW1DCH	DC9	DC8	DC7	DC6	DC5	DC4	DC3	DC2	xxxx xxxx	uuuu uuuu
13h, Bank 3	PW2DCH	DC9	DC8	DC7	DC6	DC5	DC4	DC3	DC2	xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented read as a '0', q - value depends on condition, shaded cells are not used by Timer1 or Timer2.

Note 1: Other (non power-up) resets include: external reset through $\overline{MCLR}$ and WDT Timer Reset.

12.1.3.1 PWM PERIODS

The period of the PWM1 output is determined by Timer1 and its period register (PR1). The period of the PWM2 output can be software configured to use either Timer1 or Timer2 as the time-base. When TM2PW2 bit (PW2DCL<5>) is clear, the time-base is determined by TMR1 and PR1. When TM2PW2 is set, the time-base is determined by Timer2 and PR2.

Running two different PWM outputs on two different timers allows different PWM periods. Running both PWMs from Timer1 allows the best use of resources by freeing Timer2 to operate as an 8-bit timer. Timer1 and Timer2 can not be used as a 16-bit timer if either PWM is being used.

The PWM periods can be calculated as follows:

period of PWM1 =[(PR1) + 1] x 4TOSC

period of PWM2 =[(PR1) + 1] x 4TOSC or
[(PR2) + 1] x 4TOSC

The duty cycle of PWMx is determined by the 10-bit value DCx<9:0>. The upper 8-bits are from register PWxDCH and the lower 2-bits are from PWxDCL<7:6> (PWxDCH:PWxDCL<7:6>). Table 12-3 shows the maximum PWM frequency (FPWM) given the value in the period register.

The number of bits of resolution that the PWM can achieve depends on the operation frequency of the device as well as the PWM frequency (FPWM).

Maximum PWM resolution (bits) for a given PWM frequency:

$$= \frac{\log\left(\frac{FOSC}{FPWM}\right)}{\log(2)} \text{ bits}$$

The PWMx duty cycle is as follows:

PWMx Duty Cycle = (DCx) x TOSC

where DCx represents the 10-bit value from PWxDCH:PWxDCL.

If DCx = 0, then the duty cycle is zero. If PRx = PWxDCH, then the PWM output will be low for one to four Q-clock (depending on the state of the PWxDCL<7:6> bits). For a Duty Cycle to be 100%, the PWxDCH value must be greater then the PRx value.

The duty cycle registers for both PWM outputs are double buffered. When the user writes to these registers, they are stored in master latches. When TMR1 (or TMR2) overflows and a new PWM period begins, the master latch values are transferred to the slave latches and the PWMx pin is forced high.

Note:	For PW1DCH, PW1DCL, PW2DCH and PW2DCL registers, a write operation writes to the "master latches" while a read operation reads the "slave latches". As a result, the user may not read back what was just written to the duty cycle registers.

The user should also avoid any "read-modify-write" operations on the duty cycle registers, such as: ADDWF PW1DCH. This may cause duty cycle outputs that are unpredictable.

TABLE 12-3: PWM FREQUENCY vs. RESOLUTION AT 25 MHz

PWM Frequency	Frequency (kHz)				
	24.4	**48.8**	**65.104**	**97.66**	**390.6**
PRx Value	0xFF	0x7F	0x5F	0x3F	0x0F
High Resolution	10-bit	9-bit	8.5-bit	8-bit	6-bit
Standard Resolution	8-bit	7-bit	6.5-bit	6-bit	4-bit

12.1.3.2 PWM INTERRUPTS

The PWM module makes use of TMR1 or TMR2 interrupts. A timer interrupt is generated when TMR1 or TMR2 equals its period register and is cleared to zero. This interrupt also marks the beginning of a PWM cycle. The user can write new duty cycle values before the timer roll-over. The TMR1 interrupt is latched into the TMR1IF bit and the TMR2 interrupt is latched into the TMR2IF bit. These flags must be cleared in software.

12.1.3.3 EXTERNAL CLOCK SOURCE

The PWMs will operate regardless of the clock source of the timer. The use of an external clock has ramifications that must be understood. Because the external TCLK12 input is synchronized internally (sampled once per instruction cycle), the time TCLK12 changes to the time the timer increments will vary by as much as TCY (one instruction cycle). This will cause jitter in the duty cycle as well as the period of the PWM output.

This jitter will be ±TCY, unless the external clock is synchronized with the processor clock. Use of one of the PWM outputs as the clock source to the TCLKx input, will supply a synchronized clock.

In general, when using an external clock source for PWM, its frequency should be much less than the device frequency (Fosc).

12.2.1 ONE CAPTURE AND ONE PERIOD REGISTER MODE

In this mode registers PR3H/CA1H and PR3L/CA1L constitute a 16-bit period register. A block diagram is shown in Figure 12-7. The timer increments until it equals the period register and then resets to 0000h. TMR3 Interrupt Flag bit (TMR3IF) is set at this point. This interrupt can be disabled by clearing the TMR3 Interrupt Enable bit (TMR3IE). TMR3IF must be cleared in software.

This mode is selected if control bit CA1/$\overline{PR3}$ is clear. In this mode, the Capture1 register, consisting of high byte (PR3H/CA1H) and low byte (PR3L/CA1L), is configured as the period control register for TMR3. Capture1 is disabled in this mode, and the corresponding Interrupt bit CA1IF is never set. TMR3 increments until it equals the value in the period register and then resets to 0000h.

Capture2 is active in this mode. The CA2ED1 and CA2ED0 bits determine the event on which capture will occur. The possible events are:

- Capture on every falling edge
- Capture on every rising edge
- Capture every 4th rising edge
- Capture every 16th rising edge

When a capture takes place, an interrupt flag is latched into the CA2IF bit. This interrupt can be enabled by setting the corresponding mask bit CA2IE. The Peripheral Interrupt Enable bit (PEIE) must be set and the Global Interrupt Disable bit (GLINTD) must be cleared for the interrupt to be acknowledged. The CA2IF interrupt flag bit must be cleared in software.

When the capture prescale select is changed, the prescaler is not reset and an event may be generated. Therefore, the first capture after such a change will be ambiguous. However, it sets the time-base for the next capture. The prescaler is reset upon chip reset.

Capture pin RB1/CAP2 is a multiplexed pin. When used as a port pin, Capture2 is not disabled. However, the user can simply disable the Capture2 interrupt by clearing CA2IE. If RB1/CAP2 is used as an output pin, the user can activate a capture by writing to the port pin. This may be useful during development phase to emulate a capture interrupt.

The input on capture pin RB1/CAP2 is synchronized internally to internal phase clocks. This imposes certain restrictions on the input waveform (see the Electrical Specification section for timing).

The Capture2 overflow status flag bit is double buffered. The master bit is set if one captured word is already residing in the Capture2 register and another "event" has occurred on the RB1/CA2 pin. The new event will not transfer the Timer3 value to the capture register, protecting the previous unread capture value. When the user reads both the high and the low bytes (in any order) of the Capture2 register, the master overflow bit is transferred to the slave overflow bit (CA2OVF) and then the master bit is reset. The user can then read TCON2 to determine the value of CA2OVF.

The recommended sequence to read capture registers and capture overflow flag bits is shown in Example 12-1.

EXAMPLE 12-1: SEQUENCE TO READ CAPTURE REGISTERS

```
MOVLB 3               ;Select Bank 3
MOVPF CA2L,LO_BYTE    ;Read Capture2 low
                      ;byte, store in LO_BYTE
MOVPF CA2H,HI_BYTE    ;Read Capture2 high
                      ;byte, store in HI_BYTE
MOVPF TCON2,STAT_VAL  ;Read TCON2 into file
                      ;STAT_VAL
```

FIGURE 12-7: TIMER3 WITH ONE CAPTURE AND ONE PERIOD REGISTER BLOCK DIAGRAM

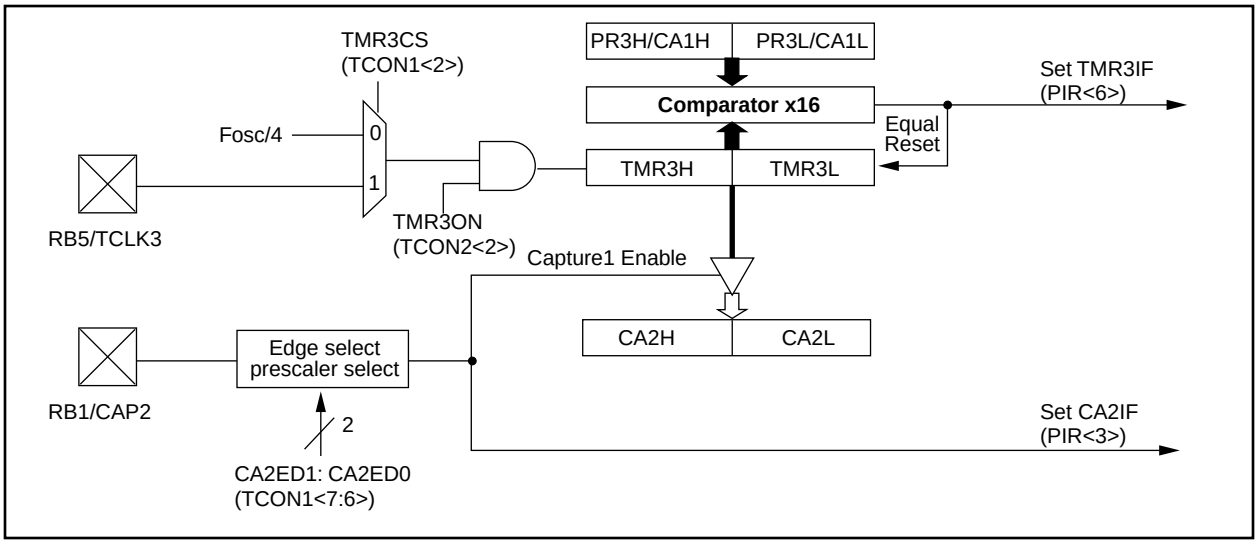


FIGURE 12-10: TMR1, TMR2, AND TMR3 OPERATION IN TIMER MODE

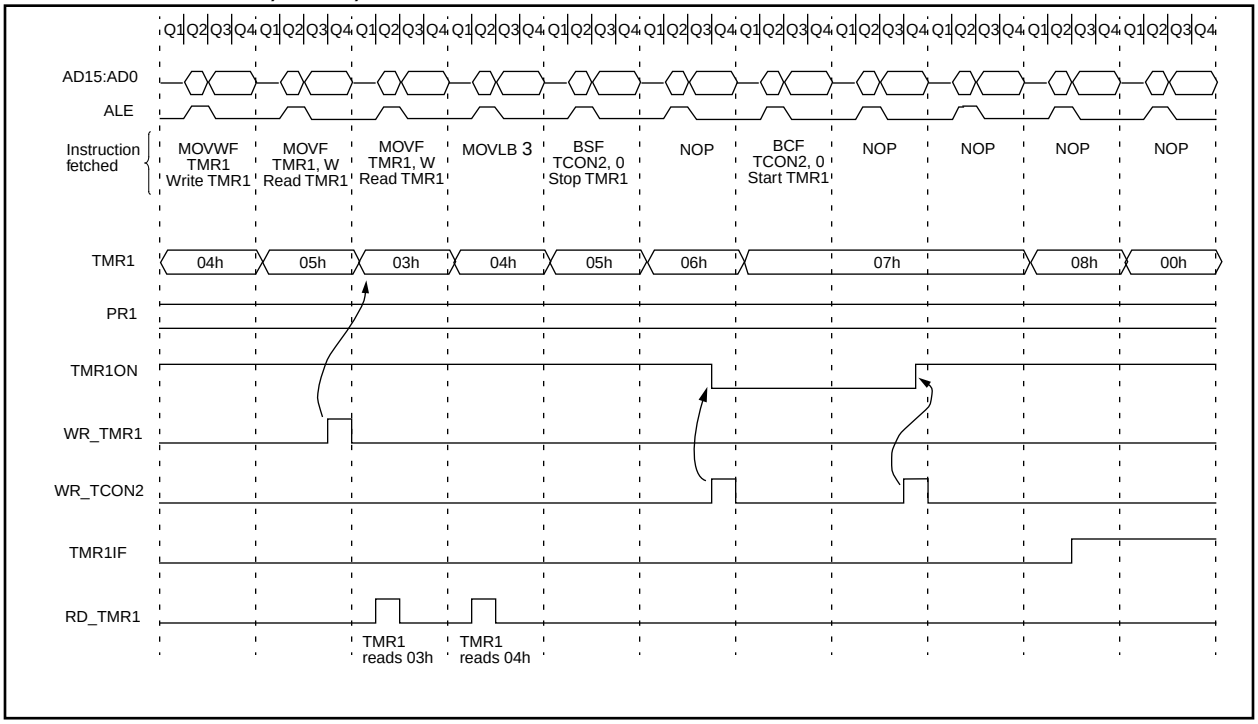


TABLE 12-6: SUMMARY OF TMR1, TMR2, AND TMR3 REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other resets (Note1)
16h, Bank 3	TCON1	CA2ED1	CA2ED0	CA1ED1	CA1ED0	T16	TMR3CS	TMR2CS	TMR1CS	0000 0000	0000 0000
17h, Bank 3	TCON2	CA2OVF	CA1OVF	PWM2ON	PWM1ON	CA1/$\overline{PR3}$	TMR3ON	TMR2ON	TMR1ON	0000 0000	0000 0000
10h, Bank 2	TMR1	Timer1 register								xxxx xxxx	uuuu uuuu
11h, Bank 2	TMR2	Timer2 register								xxxx xxxx	uuuu uuuu
12h, Bank 2	TMR3L	TMR3 register; low byte								xxxx xxxx	uuuu uuuu
13h, Bank 2	TMR3H	TMR3 register; high byte								xxxx xxxx	uuuu uuuu
16h, Bank 1	PIR	RBIF	TMR3IF	TMR2IF	TMR1IF	CA2IF	CA1IF	TXIF	RCIF	0000 0010	0000 0010
17h, Bank 1	PIE	RBIE	TMR3IE	TMR2IE	TMR1IE	CA2IE	CA1IE	TXIE	RCIE	0000 0000	0000 0000
07h, Unbanked	INTSTA	PEIF	T0CKIF	T0IF	INTF	PEIE	T0CKIE	T0IE	INTE	0000 0000	0000 0000
06h, Unbanked	CPUSTA	—	—	STKAV	GLINTD	$\overline{TO}$	$\overline{PD}$	—	—	--11 11--	--11 qq--
14h, Bank 2	PR1	Timer1 period register								xxxx xxxx	uuuu uuuu
15h, Bank 2	PR2	Timer2 period register								xxxx xxxx	uuuu uuuu
16h, Bank 2	PR3L/CA1L	Timer3 period/capture1 register; low byte								xxxx xxxx	uuuu uuuu
17h, Bank 2	PR3H/CA1H	Timer3 period/capture1 register; high byte								xxxx xxxx	uuuu uuuu
10h, Bank 3	PW1DCL	DC1	DC0	—	—	—	—	—	—	xx-- ----	uu-- ----
11h, Bank 3	PW2DCL	DC1	DC0	TM2PW2	—	—	—	—	—	xx0- ----	uu0- ----
12h, Bank 3	PW1DCH	DC9	DC8	DC7	DC6	DC5	DC4	DC3	DC2	xxxx xxxx	uuuu uuuu
13h, Bank 3	PW2DCH	DC9	DC8	DC7	DC6	DC5	DC4	DC3	DC2	xxxx xxxx	uuuu uuuu
14h, Bank 3	CA2L	Capture2 low byte								xxxx xxxx	uuuu uuuu
15h, Bank 3	CA2H	Capture2 high byte								xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented read as '0', q - value depends on condition, shaded cells are not used by TMR1, TMR2 or TMR3.

Note 1: Other (non power-up) resets include: external reset through $\overline{MCLR}$ and WDT Timer Reset.

TABLE 13-8: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER RECEPTION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other resets (Note1)
16h, Bank 1	PIR	RBIF	TMR3IF	TMR2IF	TMR1IF	CA2IF	CA1IF	TXIF	RCIF	0000 0010	0000 0010
13h, Bank 0	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00u
14h, Bank 0	RCREG	RX7	RX6	RX5	RX4	RX3	RX2	RX1	RX0	xxxx xxxx	uuuu uuuu
17h, Bank 1	PIE	RBIE	TMR3IE	TMR2IE	TMR1IE	CA2IE	CA1IE	TXIE	RCIE	0000 0000	0000 0000
15h, Bank 0	TXSTA	CSRC	TX9	TXEN	SYNC	—	—	TRMT	TX9D	0000 --1x	0000 --1u
17h, Bank 0	SPBRG	Baud rate generator register								xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented read as a '0', shaded cells are not used for synchronous master reception.

Note 1: Other (non power-up) resets include: external reset through $\overline{\text{MCLR}}$ and Watchdog Timer Reset.

CPFSLT — **Compare f with WREG, skip if f < WREG**

Syntax: [*label*] CPFSLT f

Operands: $0 \le f \le 255$

Operation: (f) – (WREG), skip if (f) < (WREG) (unsigned comparison)

Status Affected: None

Encoding:

0011	0000	ffff	ffff

Description: Compares the contents of data memory location 'f' to the contents of WREG by performing an unsigned subtraction.

If the contents of 'f' < the contents of WREG, then the fetched instruction is discarded and an NOP is executed instead making this a two-cycle instruction.

Words: 1

Cycles: 1 (2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	NOP

If skip:

Q1	Q2	Q3	Q4
Forced NOP	NOP	Execute	NOP

Example:

```
HERE    CPFSLT REG
NLESS   :
LESS    :
```

Before Instruction
PC = Address (HERE)
W = ?

After Instruction
If REG < WREG;
PC = Address (LESS)
If REG ≥ WREG;
PC = Address (NLESS)

DAW — **Decimal Adjust WREG Register**

Syntax: [*label*] DAW f,s

Operands: $0 \le f \le 255$
$s \in [0,1]$

Operation:
If [WREG<3:0> >9] .OR. [DC = 1] then
  WREG<3:0> + 6 → f<3:0>, s<3:0>;
else
  WREG<3:0> → f<3:0>, s<3:0>;

If [WREG<7:4> >9] .OR. [C = 1] then
  WREG<7:4> + 6 → f<7:4>, s<7:4>
else
  WREG<7:4> → f<7:4>, s<7:4>

Status Affected: C

Encoding:

0010	111s	ffff	ffff

Description: DAW adjusts the eight bit value in WREG resulting from the earlier addition of two variables (each in packed BCD format) and produces a correct packed BCD result.

s = 0: Result is placed in Data memory location 'f' and WREG.

s = 1: Result is placed in Data memory location 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write register 'f' and other specified register

Example1:

```
DAW   REG1, 0
```

Before Instruction
WREG = 0xA5
REG1 = ??
C = 0
DC = 0

After Instruction
WREG = 0x05
REG1 = 0x05
C = 1
DC = 0

Example 2:

Before Instruction
WREG = 0xCE
REG1 = ??
C = 0
DC = 0

After Instruction
WREG = 0x24
REG1 = 0x24
C = 1
DC = 0

RETURN **Return from Subroutine**

Syntax: [*label*] RETURN

Operands: None

Operation: TOS → PC;

Status Affected: None

Encoding:

0000	0000	0000	0010

Description: Return from subroutine. The stack is popped and the top of the stack (TOS) is loaded into the program counter.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register PCL*	Execute	NOP
Forced NOP	NOP	Execute	NOP

* Remember reading PCL causes PCLATH to be updated. This will be the high address of where the RETURN instruction is located.

Example: RETURN

After Interrupt
PC = TOS

RLCF **Rotate Left f through Carry**

Syntax: [*label*] RLCF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

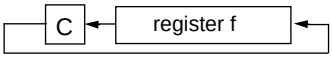
Operation: f<n> → d<n+1>;
f<7> → C;
C → d<0>

Status Affected: C

Encoding:

0001	101d	ffff	ffff

Description: The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is stored back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example:
```
RLCF    REG,0
```

Before Instruction
```
REG  =  1110 0110
C    =  0
```

After Instruction
```
REG  =  1110 0110
WREG =  1100 1100
C    =  1
```

Applicable Devices	42	R42	42A	43	R43	44

TABLE 17-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

OSC	PIC17C42-16	PIC17C42-25
RC	VDD: 4.5V to 5.5V IDD: 6 mA max. IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 6 mA max. IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 4 MHz max.
XT	VDD: 4.5V to 5.5V IDD: 24 mA max. IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 16 MHz max.	VDD: 4.5V to 5.5V IDD: 38 mA max. IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 25 MHz max.
EC	VDD: 4.5V to 5.5V IDD: 24 mA max. IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 16 MHz max.	VDD: 4.5V to 5.5V IDD: 38 mA max. IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 25 MHz max.
LF	VDD: 4.5V to 5.5V IDD: 150 μA max. at 32 kHz (WDT enabled) IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 2 MHz max.	VDD: 4.5V to 5.5V IDD: 150 μA max. at 32 kHz (WDT enabled) IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 2 MHz max.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 17-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

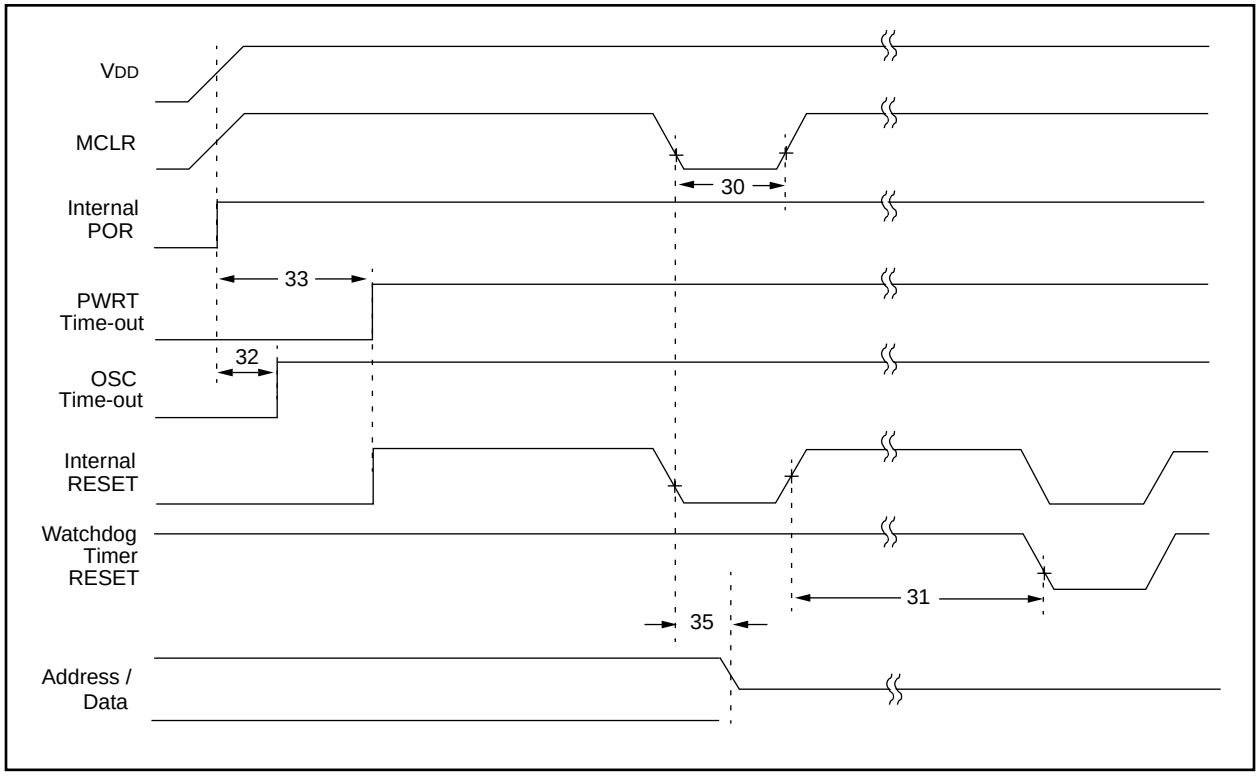


TABLE 17-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	100 *	—	—	ns	
31	Twdt	Watchdog Timer Time-out Period (Prescale = 1)	5 *	12	25 *	ms	
32	Tost	Oscillation Start-up Timer Period		1024 TOSC §		ms	TOSC = OSC1 period
33	Tpwrt	Power-up Timer Period	40 *	96	200 *	ms	
35	TmcL2adl	$\overline{\text{MCLR}}$ to System Interface bus (AD15:AD0) invalid	—	—	100 *	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

§ This specification ensured by design.

Applicable Devices	42	R42	42A	43	R43	44

19.0 PIC17CR42/42A/43/R43/44 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias ..... -55 to +125˚C

Storage temperature ..... -65˚C to +150˚C

Voltage on V_{DD} with respect to V_{SS} ..... 0 to +7.5V

Voltage on $\overline{MCLR}$ with respect to V_{SS} (Note 2) ..... -0.6V to +14V

Voltage on RA2 and RA3 with respect to V_{SS} ..... -0.6V to +14V

Voltage on all other pins with respect to V_{SS} ..... -0.6V to V_{DD} + 0.6V

Total power dissipation (Note 1) 1.0W

Maximum current out of V_{SS} pin(s) - total ..... 250 mA

Maximum current into V_{DD} pin(s) - total ..... 200 mA

Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA

Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA

Maximum output current sunk by any I/O pin (except RA2 and RA3) ..... 35 mA

Maximum output current sunk by RA2 or RA3 pins ..... 60 mA

Maximum output current sourced by any I/O pin ..... 20 mA

Maximum current sunk by PORTA and PORTB (combined) ..... 150 mA

Maximum current sourced by PORTA and PORTB (combined) ..... 100 mA

Maximum current sunk by PORTC, PORTD and PORTE (combined) ..... 150 mA

Maximum current sourced by PORTC, PORTD and PORTE (combined) ..... 100 mA

Note 1: Power dissipation is calculated as follows: $Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

Note 2: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 20-13: WDT TIMER TIME-OUT PERIOD vs. VDD

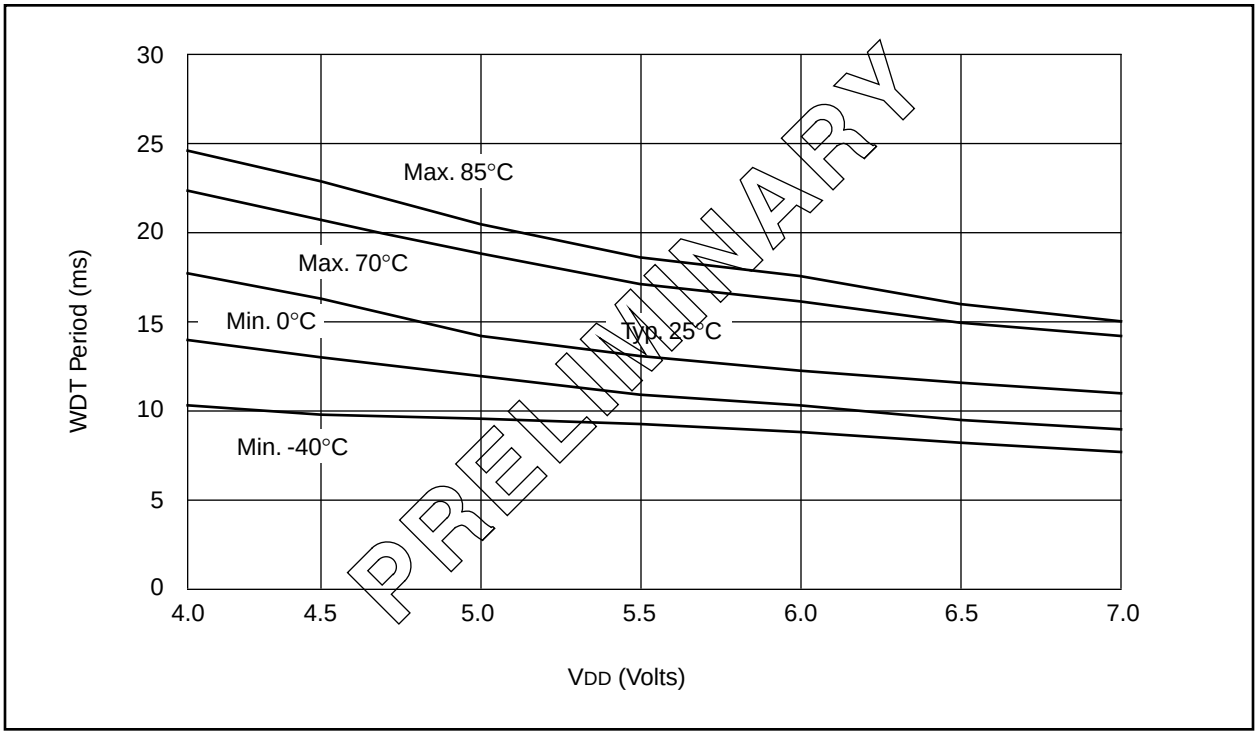
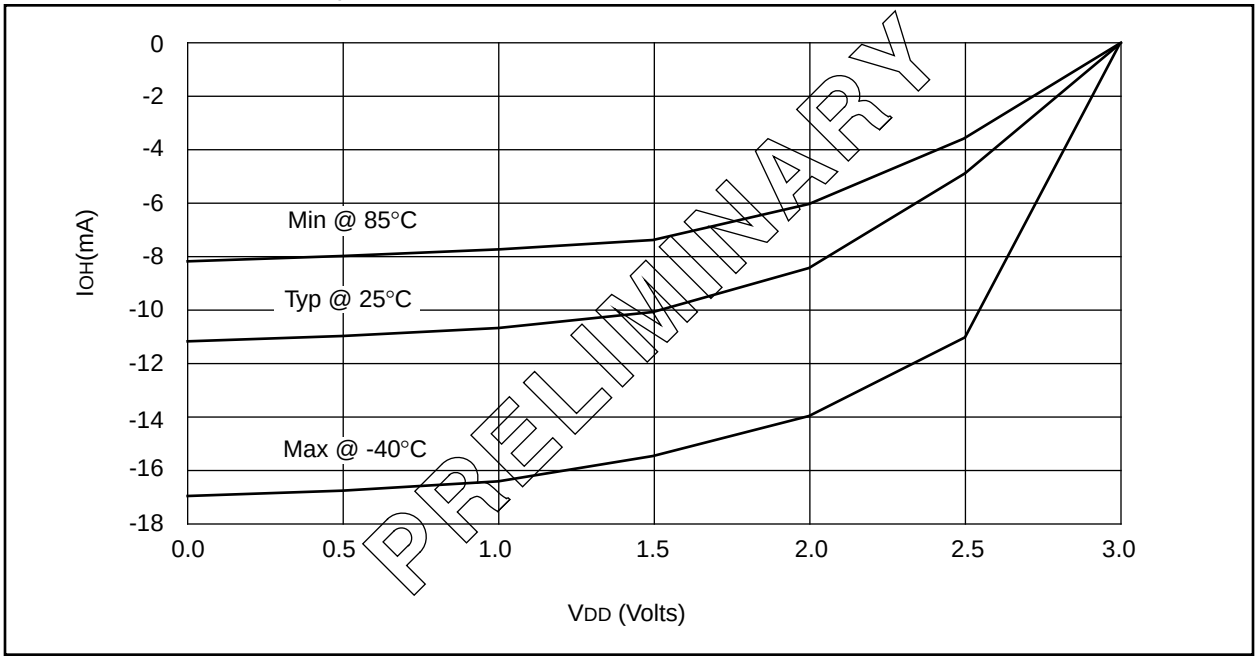
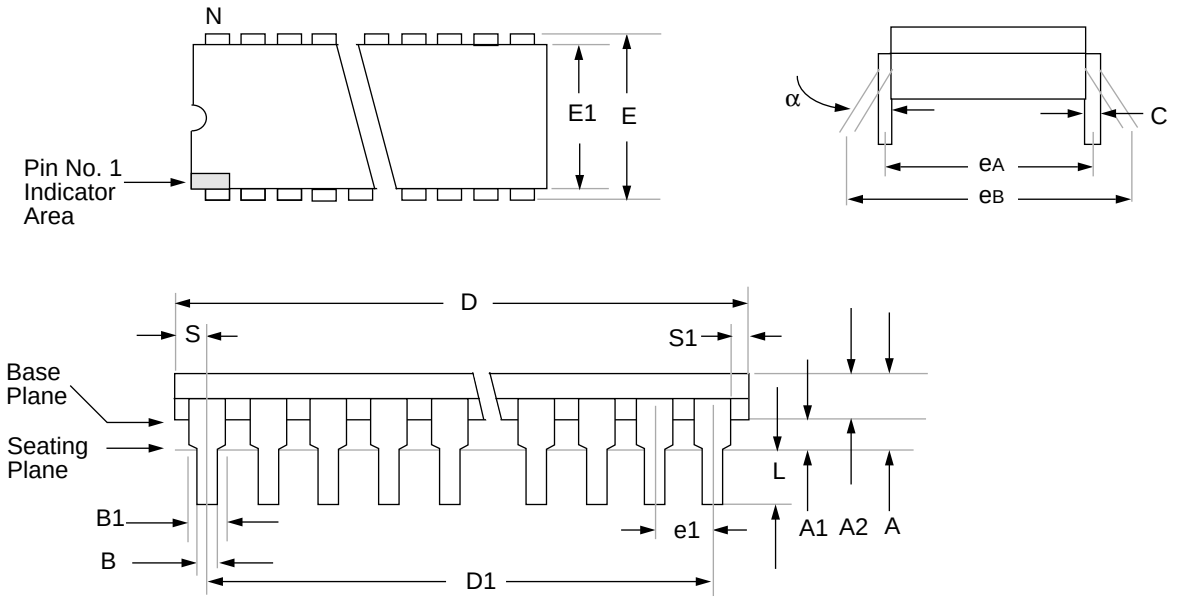


FIGURE 20-14: IOH vs. VOH, VDD = 3V



21.2 40-Lead Plastic Dual In-line (600 mil)



Package Group: Plastic Dual In-Line (PLA)						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	–	5.080		–	0.200	
A1	0.381	–		0.015	–	
A2	3.175	4.064		0.125	0.160	
B	0.355	0.559		0.014	0.022	
B1	1.270	1.778	**Typical**	0.050	0.070	**Typical**
C	0.203	0.381	**Typical**	0.008	0.015	**Typical**
D	51.181	52.197		2.015	2.055	
D1	48.260	48.260	**Reference**	1.900	1.900	**Reference**
E	15.240	15.875		0.600	0.625	
E1	13.462	13.970		0.530	0.550	
e1	2.489	2.591	**Typical**	0.098	0.102	**Typical**
eA	15.240	15.240	**Reference**	0.600	0.600	**Reference**
eB	15.240	17.272		0.600	0.680	
L	2.921	3.683		0.115	0.145	
N	40	40		40	40	
S	1.270	–		0.050	–	
S1	0.508	–		0.020	–	

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NOTES: